

# SOT1851-1

plastic very thin fine-pitch ball grid array package, 36 balls

25 April 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	VFPGA36
<b>Package type industry code</b>	VFPGA36
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	8-2-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.5	-	2.6	2.7	mm
E	package width	2.5	-	2.6	2.7	mm
A	seated height	0.8	-	0.9	1	mm
A <sub>2</sub>	package height	0.65	-	0.7	0.75	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	36	-	



## 2. Package outline

VFBGA36: plastic very thin fine-pitch ball grid array package; 36 balls

SOT1851-1

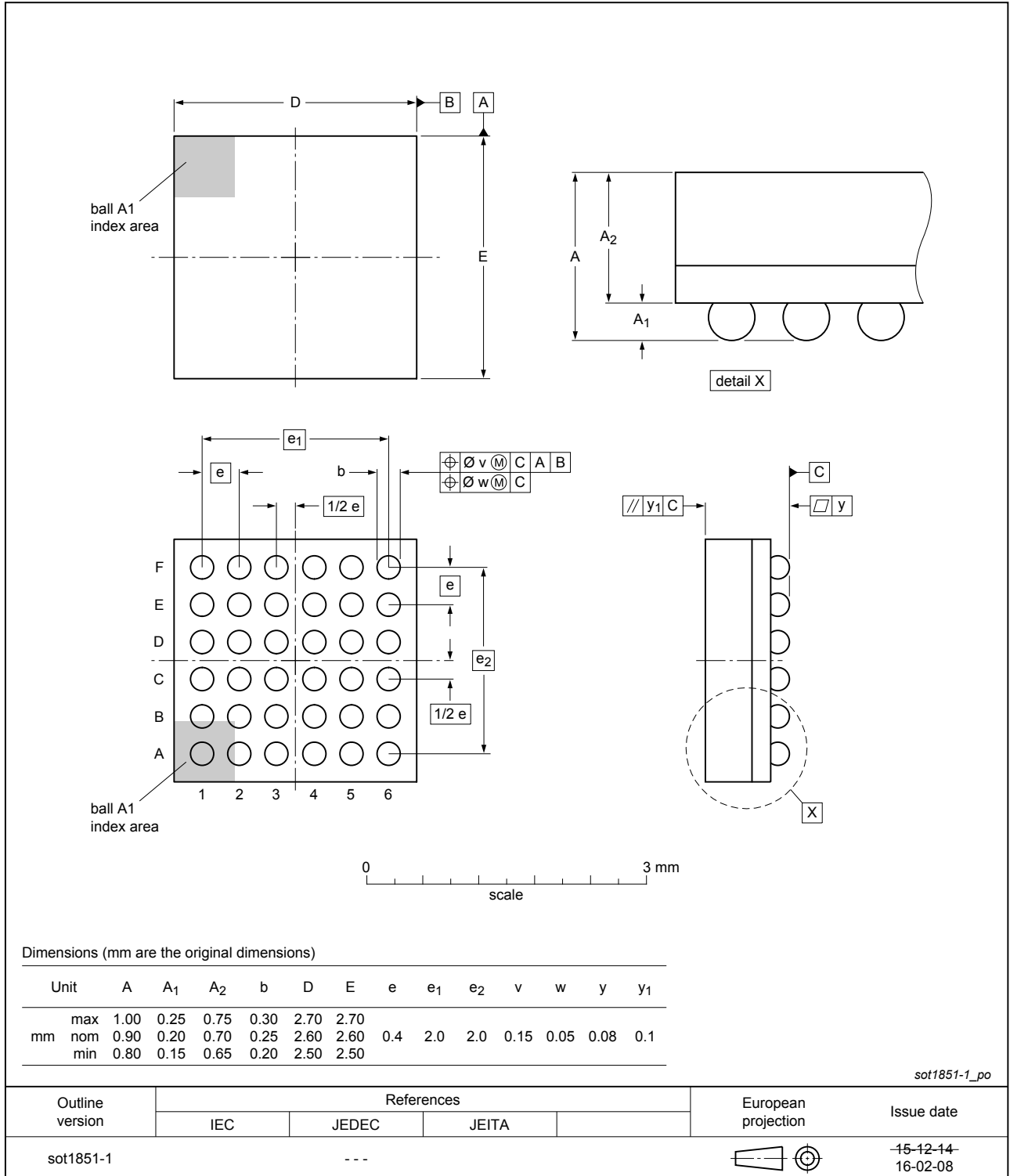


Fig. 1. Package outline VFBGA36 (SOT1851-1)

### 3. Soldering

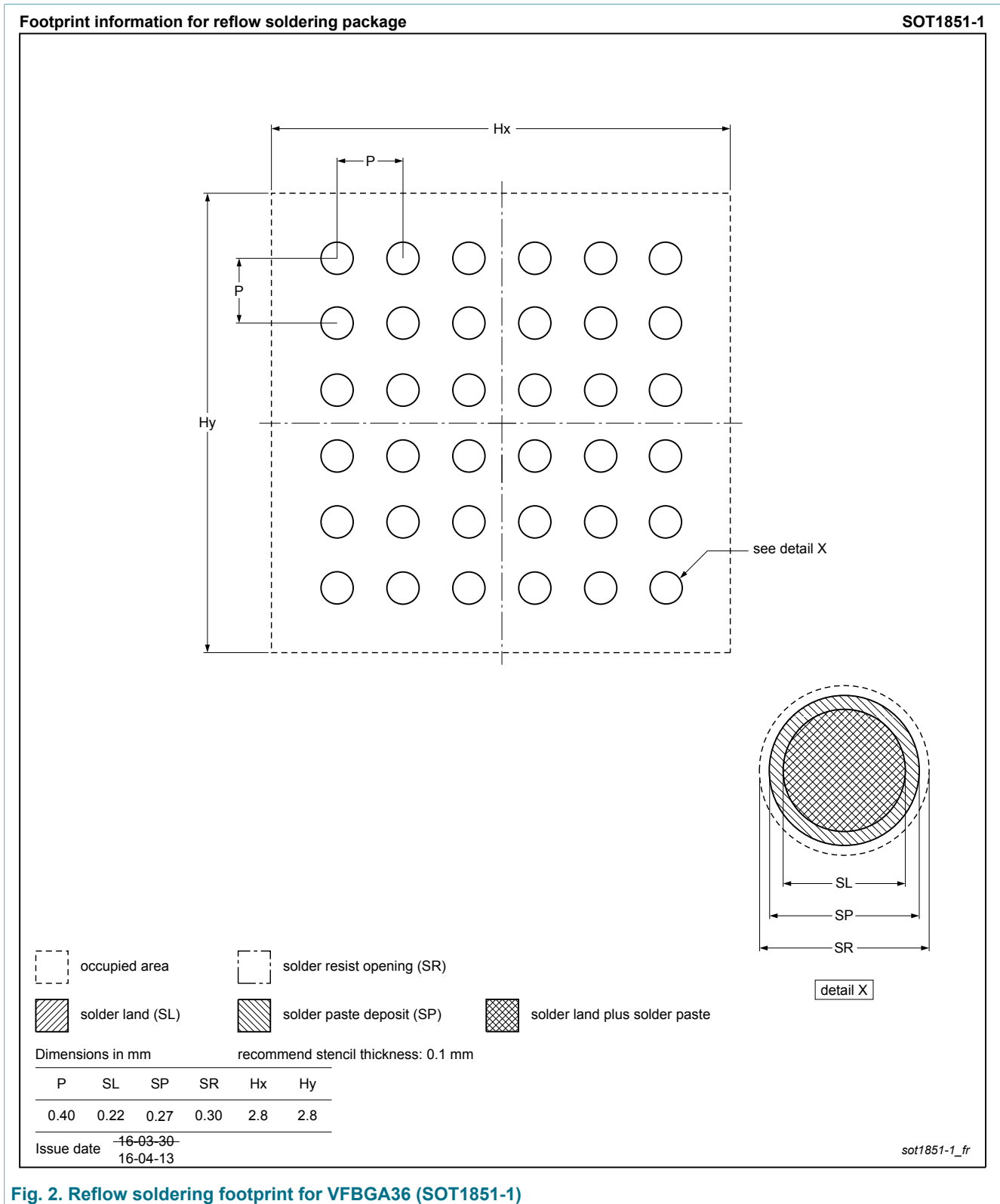


Fig. 2. Reflow soldering footprint for VFBGA36 (SOT1851-1)

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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